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Cont.

measuring the voltage of the test pin 37. As illustrated in FIG. 3D, when testing the electrical connection between the wires 25 and 26 and the IP 24, a logic voltage (e.g., H) such that the output of the ground line 41 is selected is supplied to the selector 44 from the test pin 35 via the test pad 27. Then, if the electrical connection is good, the ground voltage VSS is output to the test pin 36 via the test pad 28. Therefore, the condition of the electrical connection can be determined by measuring the voltage of the test pin 36.--

IN THE CLAIMS

Please amend claims 4 and 5 to read as follows:

4. The semiconductor device of claim 1, wherein:

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the circuit of the chip IP includes a power supply line for supplying a power supply voltage and a node, and a protection diode between the power supply line and the node; and

said at least one test pad includes a first test pad connected to a wire that is connected to the power supply line and a second test pad connected to a wire that is connected to the node in the circuit.

5. The semiconductor device of claim 1, wherein:

the circuit of the chip IP includes a ground line for supplying a ground voltage and a node, and a protection diode between the ground line and the node; and

said at least one test pad includes a first test pad connected to a wire that is connected to the ground line and a second test pad connected to a wire that is connected to the node in the circuit.

SEE APPENDIX FOR CHANGES MADE TO THE CLAIMS AND SPECIFICATION